

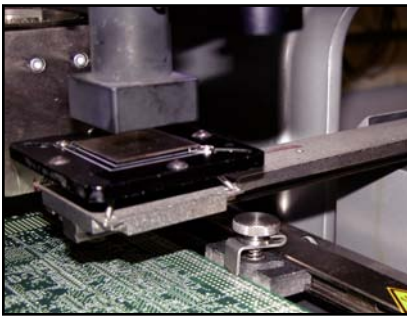
ONYX29

Options



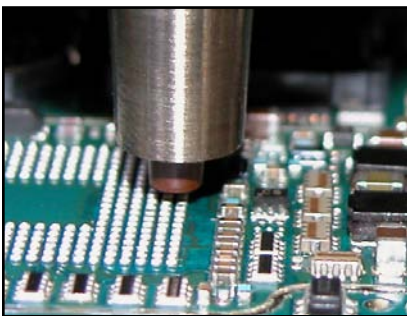
Pivoting IR Probe with Pointer #0029.11.041

- Provides process repeatability by insuring that the board is at the exact same target temperature each time before localized reflow begins.
- The laser point provides a visual reference to the center of the IR sensor verifying position over the substrate and at the same location as when profiled.
- Pivot function allows positioning on small boards without interference of the nozzle heating throughout the rework processes.
- The non-contact temperature sensor monitors topside board temp and automatically triggers the localized reflow process once the target temperature is reached.



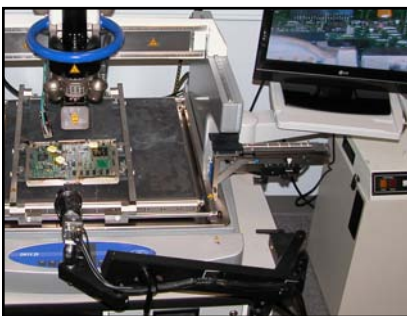
Component Shuttle #0029.02.042

- Provides a safe, repeatable location for component pick up, flux dipping and drop off away from the heated work area.
- Eliminates manual component loading and removal in the heated work area.
- Software-controlled pneumatic shuttle enters the work area for pick up, flux dipping or drop off, then exits the work area.
- Shuttle-based component pick up and flux dipping is set and monitored with machine force placement system.
- Multi-location pick and flux dipping capability for multi-processing of small devices (custom tooling required).



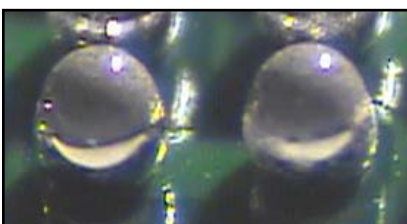
Site Cleaning System #0029.03.012

- Includes Standard and Micro nozzles.
- High temperature composite vacuum tip eliminates metal-to-metal contact.
- Vacuum sensor automatically and continuously adjusts tip height, providing non-contact site cleaning.
- Various size heating noses and tips provide the ability to clean virtually any site.
- Ready-to-use site cleaning master programs for fully automated solder removal.



Direct View Camera with 20" Video Monitor #0029.04.041

- Provides high magnification site viewing including the ability to verify when component reflow has occurred.
- Operator is instructed to position the camera on the site. Focus, zoom, and lighting adjustments are made to optimize clarity. The image is displayed on a flat screen monitor.
- A valuable process development aid especially for difficult to see tiny solder joints.
- Recommended for use in conjunction with the automatic site cleaning system to verify cleaning on dense assemblies.
- Recommended for the dispensing option to provide dispense inspection capability.



Dipping Kit for new dippable solder paste or tacky flux #FASET1

- Superior to applying paste via component or board stencils
- Easier process and less operator involvement than stencils (consistent results)
- No component or board/pad coplanarity preparation Issues
- No adjacent interference issues
- Excellent for Extremely Fine Pitch, Sphere or Leaded Size Components
- One Set of Dipping Pedestals Replaces Dozens of Custom Component Stencils



Ergonomic Workstation #1003.05.010 and Options

- Provides a self contained work cell environment for the machine and operator.
- 60"W x 36"D sturdy construction with anti-static laminate surface. Includes CPU Holder.

Options

- 1003.05.05 Monitor Stand
- 1003.05.06 Nozzle Stand
- 1003.05.07 Locking Drawer



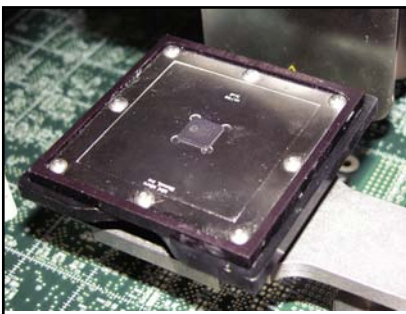
Fume Extraction Manifold & Hose Assembly #300.00.547

- Removes flux vapors from the work environment for operator health and safety.
- Includes fume extraction manifold and hose assembly.
- Requires connection to a central exhaust or self-contained filtering system.



Dispensing System #0029.08.010

- Provides on-machine dispensing of flux, solder paste, adhesive, epoxy or underfill.
- Proprietary time/pressure dispenser features automatic pressure compensation and programmable vacuum adjustment for accurate and repeatable results.
- Uses precision DL Technology dispense needles.
- Automatic pattern generation software makes creating dispensing patterns a snap.
- Note, dispensing requires ambient machine/ assembly temperature. Nozzle cool air injection and the board cooling system can be simultaneously activated to prepare the machine and assembly for dispensing, however this is not practical from a time standpoint for each individual rework process.
- The on-machine dispense option is typically used in either a batch mode or for low volume, specialty applications.



Paste-On-Device Mini Micro Stencil Adapter #0024.24.111

- Component specific stencil applies solder paste directly to the component spheres.
- Pasted device in stencil is placed in stencil adapter, which is used in conjunction with the vision system component tray to pick up the pasted device.
- Air-Vac does not supply the component-specific stencils. Recommended supplier is Mini Micro Stencil 760-591-3804.

Universal Insertion Tool #AU6LGA47R

Mechanically self-centers any square or rectangular device for accurate pick up. Used in conjunction with vision system component tray. Component Range: 6-47mm rectangular devices.

70mm (2.75") Top Side Clearance #0029.01.052

Provides increased top side clearance for assemblies with vertical daughter cards or tall devices that exceed the standard 30mm (1.2") top side clearance.

